

WHAT IS CLAIMED IS:

1. A semiconductor device having a plurality of interconnecting lines disposed side by side in a dielectric film, each interconnecting line having a top, a bottom, and a width, wherein:

the width of each interconnecting line varies from the top of the interconnecting line to the bottom of the interconnecting line; and

each mutually adjacent pair of the interconnecting lines is separated by a substantially constant distance from the top of each of the interconnecting lines in the mutually adjacent pair to the bottom of each of the interconnecting lines in the mutually adjacent pair.

2. The semiconductor device of claim 1, wherein the interconnecting lines have cross-sectional T shapes.

3. The semiconductor device of claim 2, wherein interconnecting lines having upright cross-sectional T shapes are disposed alternately with interconnecting lines having inverted cross-sectional T shapes.

4. The semiconductor device of claim 1, wherein each interconnecting line has an upper part having a first constant width and a lower part having a second constant width, the second constant width differing from the first constant width.

5. The semiconductor device of claim 4, wherein interconnecting lines in which the upper part is wider than the lower part are disposed alternately with interconnecting lines in which the lower part is wider than the upper part.

6. The semiconductor device of claim 4, wherein the upper part and the lower part have equal heights.

7. The semiconductor device of claim 6, wherein the equal heights are equal to one-half of a height of the interconnecting lines.

8. The semiconductor device of claim 1, wherein the interconnecting lines have trapezoidal shapes.

9. The semiconductor device of claim 8, wherein the trapezoidal shapes are bilaterally symmetrical.

10. The semiconductor device of claim 8, wherein each interconnecting line has a top width and a bottom width, the top width differing from the bottom width.

11. The semiconductor device of claim 10, wherein interconnecting lines in which the top width exceeds the bottom width are disposed alternately with interconnecting lines in which the bottom width exceeds the top width.